

# SOT1452-1

wafer level chip-scale package, 11 bumps

21 April 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP11
<b>Package type industry code</b>	WLCSP11
<b>Package style descriptive code</b>	WLCSP (wafer level chip-size package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	2-3-2016

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.84	-	0.87	0.9	mm
E	package width	0.64	-	0.67	0.7	mm
A	seated height	0.28	-	0.305	0.33	mm
A <sub>2</sub>	package height	0.205	-	0.225	0.245	mm
e	nominal pitch	-	-	0.67	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	11	-	



## 2. Package outline

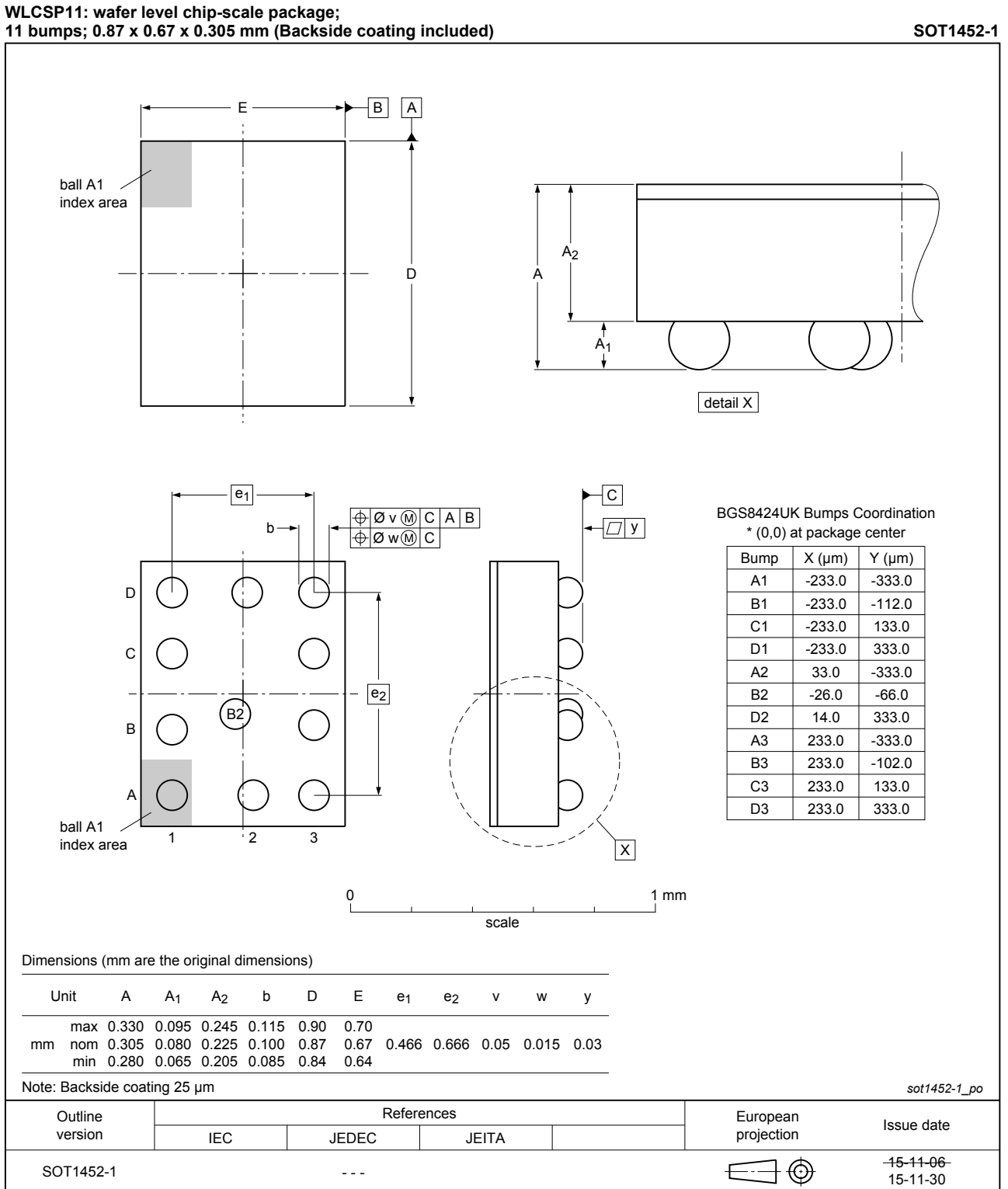


Fig. 1. Package outline WLCSP11 (SOT1452-1)

### 3. Legal information

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